

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L6	911063	mold\$3	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 10:54
L7	545154	tape\$1	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 10:54
L8	97768	polyimide	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 10:54
L9	5106	7 with 8	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 10:54
L10	21	5 same 9	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 10:54
L14	595557	adhesive	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 11:26
L15	1206	5 with 14	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 11:26
L16	182	7 same 15	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 11:35
L24	612824	(chip\$1 or die\$1 or ic or device\$1) same (semiconduct\$3 or silicon)	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 12:25
L25	937	23 and 24	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 12:25
L26	291	25 and 1	US-PGPUB; USPAT; EPO; JPO	OR	OFF	2005/01/06 12:26